LNJ252W82RA

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.4 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Lighting Color • Red

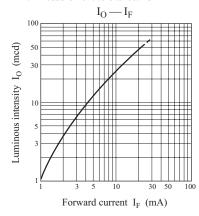
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

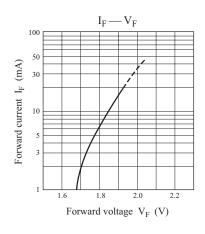
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

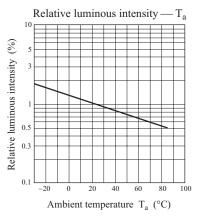
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 10 \text{ mA}$	10.0	25.0	40.0	mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		1.85	2.5	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		645		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 10 \text{ mA}$	620	630	640	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		22		nm

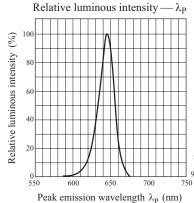
Note) *1: Measurement tolerance: ±20%

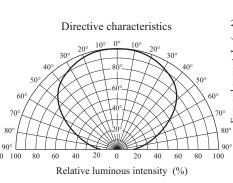
^{*2:} Measurement tolerance: ±3 nm

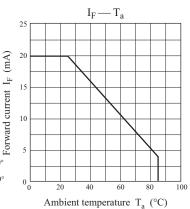








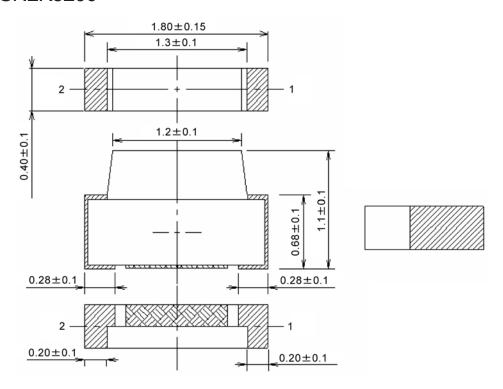




Panasonic

■ Package (Unit: mm)

KLTFSN2K5200



- Pin name
 - 1: Anode
 - 2: Cathode

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